

1. Description

The LiteON K140 Product series is a wide beam angle standard-dimension package, combining the lifetime and reliability advantages of Light Emitting Diodes with the brightness of conventional lighting. It gives you total design freedom and unmatched brightness, creating a new opportunities for solid state lighting to displace conventional lighting technologies.

1.1 Features

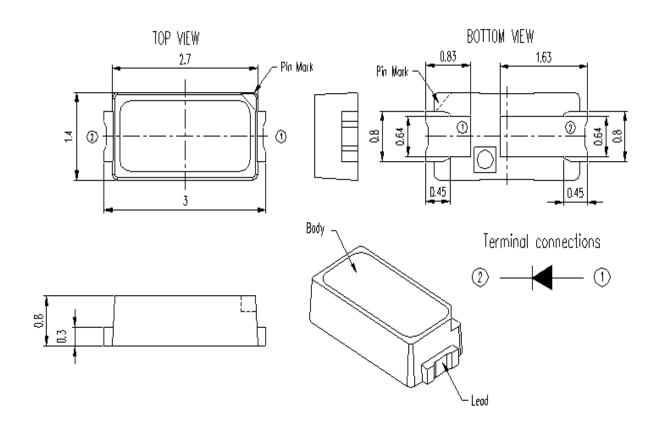
- Package in 8mm tape on 7" diameter reels.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- EIA STD package.
- I.C. compatible.
- Meet green product and Pb-free(According to RoHS)

1.2 Available Part Numbers

ССТ	Part Number
6500K	LTW-K140SZR65
5700K	LTW-K140SZR57
5000K	LTW-K140SZR50
4000K	LTW-K140SZR40
3000K	LTW-K140SZR30
2700K	LTW-K140SZR27



2. Outline Dimensions



Part No.	Lens Color	Source Color
LTW-K140SZR65		
LTW-K140SZR57		
LTW-K140SZR50	Orango	InGaN Blue
LTW-K140SZR40	Orange	IIIGaN blue
LTW-K140SZR30		
LTW-K140SZR27		

Notes:

- 1. All dimensions are in millimeters.
- 2. Tolerance is ±0.1 mm (.008") unless otherwise noted.



3. Absolute Maximum Ratings at T_a=25°C

Parameter	Symbol	Rating	Unit
Power Dissipation	Po	280	mW
Continuous Forward Current	l _F	80	mA
Operating Temperature Range	T_{opr}	-40 ~ +80	°C
Storage Temperature Range	T _{stg}	-40 ~ +100	°C
Junction Temperature	T _j	≦115	°C

Notes:

1. Forbid to operating at reverse voltage condition for long.



4. Electro-Optical Characteristics

4.1 Typical Performance

Parameter	Symbol			٧	/alues				Unit	Test Condition
Correlated Color Temperature	ССТ	Тур.	2700	3000	4000	5000	5700	6500	°K	
Chromoticity Coordinates	Х	Тур.	0.458	0.434	0.382	0.345	0.329	0.312		
Chromaticity Coordinates	у	Тур.	0.410	0.403	0.380	0.355	0.342	0.328	_	
		Min	16	17	18	19	19	18		
Luminous Flux ¹	Ф	Тур.	20.2	21.0	22.2	23.7	23.2	22.7	lm	
		Max.	24	25	26	27	27	26		
Optical Efficiency	η_{opt}	Тур.	105	109	116	123	121	118	lm/W	/ CO A
Color Rendering Index	CRI	Min.			80				-	<i>I</i> _F = 60mA
Viewing Angle	2θ _{1/2}	Тур.			120)			deg	
		Min			2.9)				
Forward Voltage	V_{F}	Тур.	3.2						V	
		Max.	с. 3.5							
Thermal Resistance	R _{jt}	Тур. 30							°C/W	
Reverse Current	I _R	Max.			100)			μΑ	$V_R = 5V$

Notes

- 1. Luminous flux is the total luminous flux output as measured with an integrating sphere.
- 2. Iv (flux Φ_v) classification code is marked on each packing bag.
- 3. The chromaticity coordinates (x, y) is derived from the 1931 CIE chromaticity diagram.
- 4. Caution in ESD:

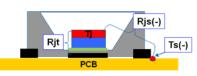
Static Electricity and surge damages the LED. It is recommended using a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

- 5. CAS140B is the test standard for the chromaticity coordinates (x, y) & Φ_{v} .
- 6. The chromaticity coordinates (x, y) guarantee should be added +/- 0.01 tolerances
- 7. CRI measurement allowance is ±5
- 8. The Thermal Resistance is defined

as the figure, Rit is the Rth from Ti to Thermal Pad Solder:

Reference for thermal resistance:

Using 2.5x 2.5x 0.17 cm Aluminum MCPCB, R_{it}=30°C/W, R_{is}=35 °C/W

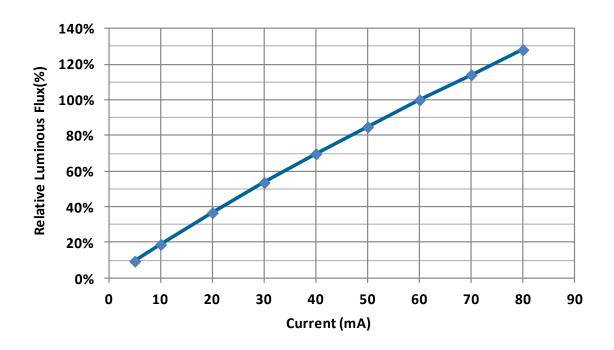


- ♦ Rjs = Rth of Tj to Ts
- ◆ Rjt = Rth of Tj to Thermal pad solder
- ◆ Rth definition in Datasheet = Rjt
- ◆ Rjt < Rjc ◆ Tj = Rjs*W+Ts



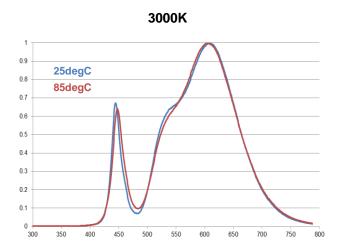
4.2 Forward Current vs. Lumen and Voltage

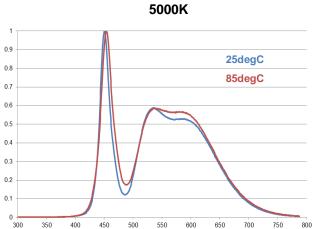
Current	VF		Lumen (Im)									
(mA)	(V)	2700K	3000K	4000K	5000K	5700K	6500K					
10	2.85	3.8	4.0	4.2	4.4	4.3	4.3					
20	2.94	7.5	7.7	8.2	8.7	8.5	8.3					
30	3.02	10.8	11.2	12.0	12.7	12.4	12.2					
40	3.08	14.1	14.6	15.6	16.5	16.2	15.8					
50	3.14	17.2	17.7	18.9	20.1	19.7	19.2					
60	3.20	20.2	21.0	22.2	23.7	23.2	22.7					
70	3.25	23.0	23.9	25.4	27.0	26.5	25.8					
80	3.31	25.9	26.8	28.5	30.3	29.7	29.1					



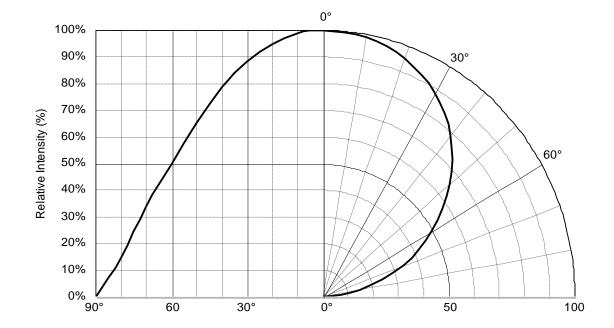


4.3 Relative Spectral Power Distribution at Typical Current



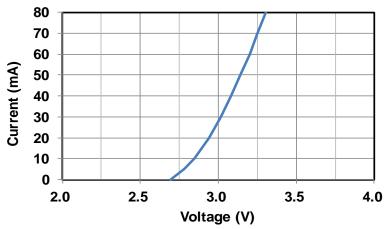


4.4 Radiation Characteristics

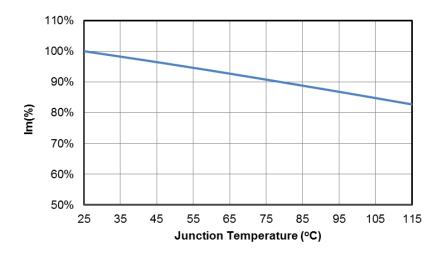




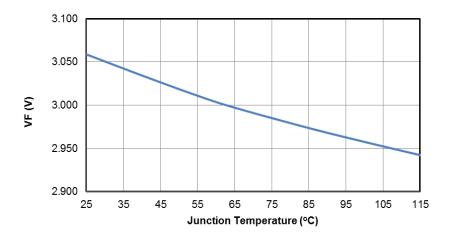
4.5 Forward Current vs. Forward Voltage



4.6 Relative Luminous Flux vs Junction Temperature



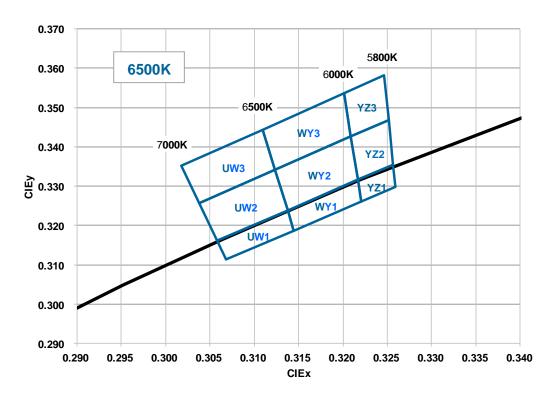
4.7 Forward Voltage vs Junction Temperature

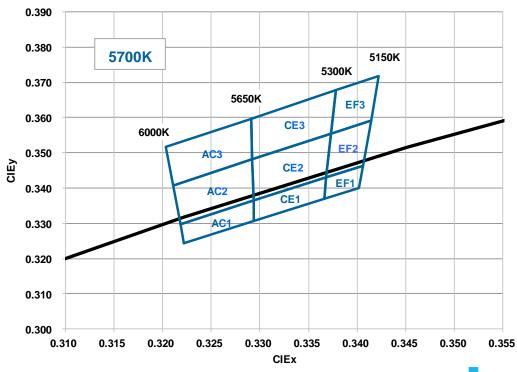




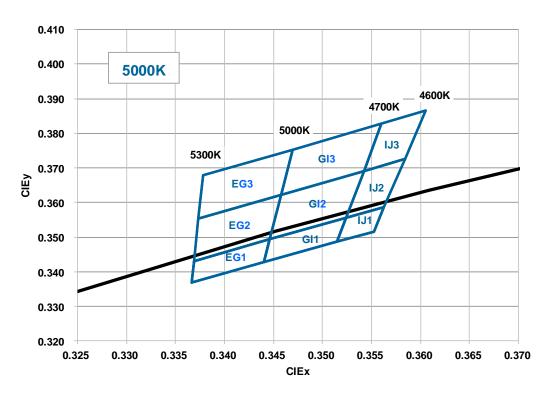
5. Binning Definition

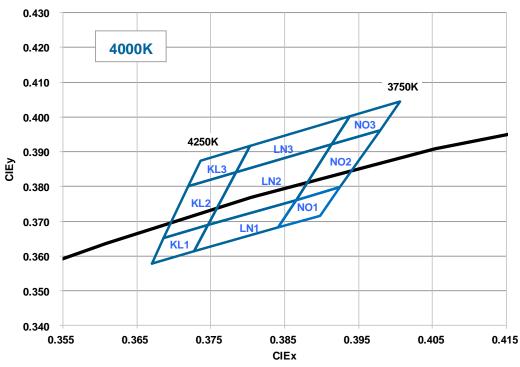
5.1 Color Bin



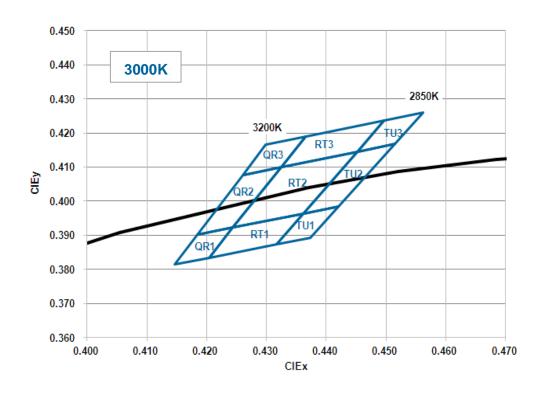


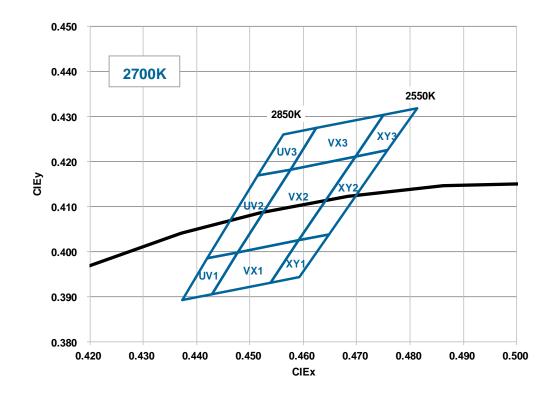














5.2 Color Rank

	6500K (<i>I_F</i> = 60 mA)										
Rank	-	х	у	Rank	-	х	у	Rank	-	х	у
	1	0.3038	0.3256		1	0.3124	0.3341		1	0.3209	0.3426
UW3	2	0.3018	0.3352	WY3	2	0.3110	0.3444	YZ3	2	0.3201	0.3536
UVVS	3	0.3110	0.3444	WIS	3	0.3201	0.3536	123	3	0.3247	0.3582
	4	0.3124	0.3341		4	0.3209	0.3426		4	0.3252	0.3468
	1	0.3058	0.3161		1	0.3138	0.3238		1	0.3217	0.3316
LINAVO	2	0.3038	0.3256	WYO	2	0.3124	0.3341	V 7 0	2	0.3209	0.3426
UW2	3	0.3124	0.3341	WY2	3	0.3209	0.3426	YZ2	3	0.3252	0.3468
	4	0.3138	0.3238		4	0.3217	0.3316		4	0.3257	0.3355
	1	0.3068	0.3113		1	0.3145	0.3187		1	0.3221	0.3261
UW1	2	0.3058	0.3161	WY1	2	0.3138	0.3238	YZ1	2	0.3217	0.3316
OWI	3	0.3138	0.3238	WII	3	0.3217	0.3316	141	3	0.3257	0.3355
	4	0.3145	0.3187		4	0.3221	0.3261		4	0.3259	0.3298

Tolerance on each Hue bin (x,y) is \pm -0.01.

	5700K (<i>I_F</i> = 60 mA)										
Rank	-	х	У	Rank	-	x	у	Rank	-	х	у
	1	0.3211	0.3407		1	0.3292	0.3481		1	0.3374	0.3554
VC3	2	0.3203	0.3517	CE3	2	0.3291	0.3597	EF3	2	0.3379	0.3678
AC3	3	0.3291	0.3597	CES	3	0.3379	0.3678	EF3	3	0.3422	0.3718
	4	0.3292	0.3481		4	0.3374	0.3554		4	0.3414	0.3591
	1	0.3218	0.3298		1	0.3293	0.3364		1	0.3369	0.3431
AC2	2	0.3211	0.3407	CE2	2	0.3292	0.3481	EF2	2	0.3374	0.3554
ACZ	3	0.3292	0.3481	CEZ	3	0.3374	0.3554	EFZ	3	0.3414	0.3591
	4	0.3293	0.3364		4	0.3369	0.3431		4	0.3406	0.3464
	1	0.3222	0.3243		1	0.3294	0.3306		1	0.3366	0.3369
AC1	2	0.3218	0.3298	CE1	2	0.3293	0.3364	EF1	2	0.3369	0.3431
ACI	3	0.3293	0.3364	CE1	3	0.3369	0.3431	EFI	3	0.3406	0.3464
	4	0.3294	0.3306		4	0.3366	0.3369		4	0.3402	0.3401

Tolerance on each Hue bin (x,y) is \pm -0.01.



	5000K (<i>I_F</i> = 60 mA)										
Rank	-	х	у	Rank	-	х	у	Rank	-	х	у
	1	0.3374	0.3554		1	0.3458	0.3623		1	0.3542	0.3692
EG3	2	0.3379	0.3678	GI3	2	0.3469	0.3753	IJ3	2	0.3560	0.3828
EGS	3	0.3469	0.3753	GIS	3	0.3560	0.3828	IJS	3	0.3605	0.3866
	4	0.3458	0.3623		4	0.3542	0.3692		4	0.3584	0.3726
	1	0.3369	0.3431		1	0.3446	0.3493		1	0.3524	0.3555
EG2	2	0.3374	0.3554	GI2	2	0.3458	0.3623	IJ2	2	0.3542	0.3692
EGZ	3	0.3458	0.3623	GIZ	3	0.3542	0.3692	IJZ	3	0.3584	0.3726
	4	0.3446	0.3493		4	0.3524	0.3555		4	0.3563	0.3586
	1	0.3366	0.3369		1	0.3441	0.3428		1	0.3515	0.3487
EG1	2	0.3369	0.3431	GI1	2	0.3446	0.3493	IJ1	2	0.3524	0.3555
EGI	3	0.3446	0.3493	GII	3	0.3524	0.3555	IJI	3	0.3563	0.3586
	4	0.3441	0.3428		4	0.3515	0.3487		4	0.3552	0.3517

Tolerance on each Hue bin (x,y) is \pm -0.01.

	4000K $(I_F = 60 \text{ mA})$										
Rank	-	х	у	Rank	-	х	у	Rank	-	х	У
	1	0.3720	0.3800		1	0.3784	0.3841		1	0.3914	0.3922
KL3	2	0.3736	0.3874	LN3	2	0.3804	0.3917	NO2	2	0.3939	0.4002
KLS	3	0.3804	0.3917	LINO	3	0.3939	0.4002	NO3	3	0.4006	0.4044
	4	0.3784	0.3841		4	0.3914	0.3922		4	0.3979	0.3962
	1	0.3687	0.3652		1	0.3746	0.3689		1	0.3865	0.3762
KL2	2	0.3720	0.3800	LN2	2	0.3784	0.3841	NO2	2	0.3914	0.3922
KLZ	3	0.3784	0.3841	LINZ	3	0.3914	0.3922	NOZ	3	0.3979	0.3962
	4	0.3746	0.3689		4	0.3865	0.3762		4	0.3925	0.3798
	1	0.3670	0.3578		1	0.3727	0.3613		1	0.3841	0.3682
KL1	2	0.3687	0.3652	LN1	2	0.3746	0.3689	NO1	2	0.3865	0.3762
KLI	3	0.3746	0.3689	LINI	3	0.3865	0.3762	NOI	3	0.3925	0.3798
	4	0.3727	0.3613		4	0.3841	0.3682		4	0.3898	0.3716

Tolerance on each Hue bin (x,y) is \pm -0.01.



	3000K (<i>I_F</i> = 60 mA)										
Rank	-	х	у	Rank	-	х	у	Rank	-	х	у
	1	0.4261	0.4077		1	0.4324	0.4100		1	0.4451	0.4146
OBa	2	0.4299	0.4165	DTO	2	0.4365	0.4189	TUO	2	0.4496	0.4236
QR3	3	0.4365	0.4189	RT3	3	0.4496	0.4236	TU3	3	0.4562	0.4260
	4	0.4324	0.4100		4	0.4451	0.4146		4	0.4515	0.4168
	1	0.4185	0.3902		1	0.4244	0.3923		1	0.4361	0.3964
QR2	2	0.4261	0.4077	RT2	2	0.4324	0.4100	TU2	2	0.4451	0.4146
QR2	3	0.4324	0.4100	KIZ	3	0.4451	0.4146	102	3	0.4515	0.4168
	4	0.4244	0.3923		4	0.4361	0.3964		4	0.4420	0.3985
	1	0.4147	0.3814		1	0.4204	0.3834		1	0.4317	0.3873
QR1	2	0.4185	0.3902	RT1	2	0.4244	0.3923	TU1	2	0.4361	0.3964
QKI	3	0.4244	0.3923	KII	3	0.4361	0.3964	101	3	0.4420	0.3985
	4	0.4204	0.3834		4	0.4317	0.3873		4	0.4373	0.3893

Tolerance on each Hue bin (x,y) is \pm -0.01.

	2700K (<i>I_F</i> = 60 mA)										
Rank	-	х	у	Rank	-	х	у	Rank	-	х	у
	1	0.4515	0.4168		1	0.4625	0.4275		1	0.4697	0.4211
111/2	2	0.4562	0.4260	WY2	2	0.4750	0.4304	vva	2	0.4750	0.4304
UV3	3	0.4625	0.4275	VX3	3	0.4697	0.4211	XY3	3	0.4813	0.4319
	4	0.4576	0.4183		4	0.4576	0.4183		4	0.4758	0.4225
	1	0.4515	0.4168		1	0.4576	0.4183		1	0.4697	0.4211
UV2	2	0.4576	0.4183	VX2	2	0.4697	0.4211	XY2	2	0.4758	0.4225
UVZ	3	0.4477	0.3998	VAZ	3	0.4591	0.4025	AIZ	3	0.4648	0.4038
	4	0.4420	0.3985		4	0.4477	0.3998		4	0.4591	0.4025
	1	0.4373	0.3893		1	0.4477	0.3998		1	0.4538	0.3931
UV1	2	0.4420	0.3985	VX1	2	0.4591	0.4025	XY1	2	0.4591	0.4025
0 7 1	3	0.4477	0.3998	VAI	3	0.4538	0.3931	AII	3	0.4648	0.4038
	4	0.4428	0.3906		4	0.4428	0.3906		4	0.4593	0.3944

Tolerance on each Hue bin (x,y) is \pm -0.01.



5.3 Flux Bin

2700K	$\Phi_{ m v}$ Luminous Flux Spec. Table								
Ф Din	Lumen (lm) at <i>l</i> _F = 60 mA								
$\Phi_{ m v}$ Bin	Min	Max							
AC	16	18							
CE	18	20							
EG	20	22							
GI	22	24							

DUUUK	$\Phi_{\rm v}$ Luminous Flux Spec. Table		
Φ Din	Lumen (lm) at $I_F = 60 \text{ mA}$		
$\Phi_{ m v}$ Bin	Min	Max	
DF	19	21	
FH	21	23	
HJ	23	25	
JL	25 27		

3000K	$\Phi_{ m v}$ Luminous Flux Spec. Table			
Φ Din	Lumen (lm) at $I_F = 60 \text{ mA}$			
$\Phi_{ m v}$ Bin	Min Max			
BD	17	19		
DF	19	21		
FH	21	23		
HJ	23 25			

5700K	$\Phi_{ m v}$ Luminous Flux Spec. Table		
Φ Die	Lumen (lm) at I _F = 60 mA Min Max		
$\Phi_{ m v}$ Bin			
DF	19	21	
FH	21	23	
HJ	23	25	
JL	25 27		

4000K	$\Phi_{ m v}$ Luminous Flux Spec. Table			
љ. Die	Lumen (lm) at I _F = 60 mA			
$\Phi_{ m v}$ Bin	Min Max			
CE	18	20		
EG	20	22		
GI	22	24		
IK	24 26			

6500K	$\Phi_{ m v}$ Luminous Flux Spec. Table		
. Diα	Lumen (lm) at $I_F = 60 \text{ mA}$		
$\Phi_{ m v}$ Bin	Min	Max	
CE	18	20	
EG	20	22	
GI	22	24	
IK	24	26	

Tolerance on each Luminous Flux bin is +/- 10%.



5.4 Voltage Bin

V _F Spec. Table				
Forward Voltage (volts) at I _F = 60 mA		(volts) at <i>I</i> _F = 60 mA		
V _F Bin	Min Max			
V1	2.9	3.1		
V2	3.1	3.2		
V3	3.2	3.3		
V4	3.3	3.5		

Tolerance on each Forward Voltage bin is +/- 0.1V

6. Bin Code List

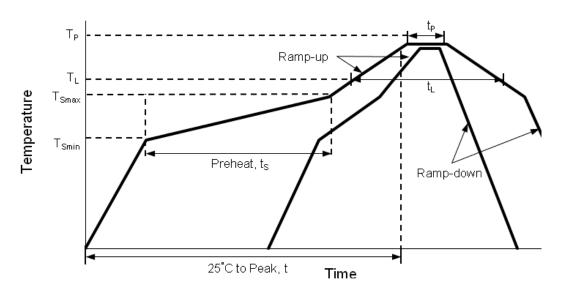
% Notes: Full Rank on Label

Example: V1/HJ/CE2

Forward Voltage Rank	Luminous Flux Rank	Color Rank
V1	HJ	CE2



7. Reflow Soldering Characteristics



Profile Feature	Lead Free Assembly
Average Ramp-Up Rate (T _{Smax} to T _P)	3°C / second max
Preheat Temperature Min (T _{Smin})	150°C
Preheat Temperature Max (T _{Smax})	200°C
Preheat Time (t _{Smin} to t _{Smax})	60 – 180 seconds
Time Maintained Above Temperature (T _L)	217°C
Time Maintained Above Time (t _L)	60 – 150 seconds
Peak / Classification Temperature (T _P)	260°C
Time Within 5°C of Actual Peak Temperature (t _P)	5 seconds
Ramp – Down Rate	6°C / second max
Time 25°C to Peak Temperature	8 minutes max

Notes:

1. The LEDs can be soldered using the reflow soldering or hand soldering method. The recommended hand



soldering condition is 350 °C max. and 2 secs max. for one time only, and the recommended reflow soldering condition is 260 °C max, and 5 secs max, for three times max.

- 2. All temperatures refer to topside of the package, measured on the package body surface.
- 3. The soldering condition referring to J-STD-020. The storage ambient for the LEDs should not exceed 30 °C temperature or 70% relative humidity. It is recommended that LEDs out of their original packaging are soldered within one week. For extended storage out of their original packaging, it is recommended that the LEDs were stored in a sealed container with appropriate desiccant, or desiccators with nitrogen ambient. If the LEDs were unpacked more than 168hrs, baking the LEDs at 60 °C for 60 mins before soldering process.
- The soldering profile could be further referred to different soldering grease material characteristic. The 4. grease vendor will provide this information.
- 5. A rapid-rate process is not recommended for the LEDs cooling down from the peak temperature.
- Although the recommended reflow conditions are specified above, the reflow or hand soldering 6. condition at the lowest possible temperature is desirable for the LEDs.
- 7. LiteOn cannot make a guarantee on the LEDs which have been already assembled using the dip soldering method.



8. Reliability Test

No	Test item	Test Condition	Duration	Number of Damaged
1	Steady State Operating Life of High Temperature (HTOL)	Ts=55°ℂ , <i>I</i> _F =60mA	1000 hrs	0/20
2	Steady State Operating Life of High Temperature (HTOL)	Ts=85°ℂ, <i>I</i> _F =60mA	1000 hrs	0/20
3	Steady State Operating Life of High Temperature (HTOL)	Ts=55°ℂ , <i>I</i> _F =80mA	1000 hrs	0/20
4	Steady State Operating Life of High Temperature (HTOL)	Ts=85°ℂ, <i>I</i> ⊧=80mA	1000 hrs	0/20
5	Steady State Operating Life of Low Temperature (LTOL)	Ta=-40°C , <i>I</i> _F =60mA	1000 hrs	0/20
6	Pulse Wet Operating Life of High Temperature (PWHTOL)	60°C/90%RH, <i>I</i> _F =60mA 30mins ON/30min OFF	500 hrs	0/20
7	High Temperature Storage (HTS)	100℃	1000 hrs	0/20
8	Low Temperature Storage (LTS)	-40 °C	1000 hrs	0/20
9	Thermal Cycle (TC)	-40°C ~100°C 30min dwell 5min transfer	200 cycle	0/20
10	Thermal Shock (TS)	-40°C ~100°C 20min dwell 20sec transfer	200 cycle	0/20
11	Solder Resistance (SR)	265℃, 3X MSL	5sec	0/20
12	Solder Ability (SA)	245°ℂ5sec, 95% coverage	5sec	0/11
13	Mechanical Shock (MS)	1500G 0.5msec pulse shock	each 6 axis	0/6
14	Random Vibration (RV)	6G RMS, 10-2000Hz, 10min	per axis	0/6
15	Variable Vibration Frequency (VVF)	10-2000-10Hz, log or linear sweep rate, 20G for 1 min, 1.5mm each apply 3x per axis	over 6hrs	0/6
16	Salt Spread (SS)	35℃, 30g/m²/day	48hrs	0/11





Criteria for Judging the Damage

Hom	Cumbal	Test Condition	Criteria for	Judgment	
Item	Symbol	rest Condition	Min. Max.		
Forward Voltage	Vf	<i>I</i> ⊧=Typical Current		U.S.L. x 1.1	
Luminous Flux	Lm	<i>I</i> _F =Typical Current	L.S.L. x 0.7		
CCX&CCY	x,y	<i>I</i> _F =Typical Current		Shift<0.02	



9. User Guide

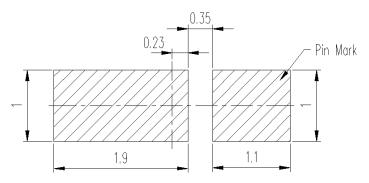
Cleaning

Do not use unspecified chemical liquid to clean LED they could harm the package. If cleaning is necessary, immerse the LED in ethyl alcohol or isopropyl alcohol at normal temperature for less than one minute.

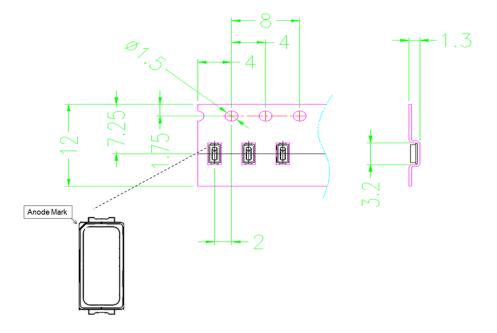
Recommend Printed Circuit Board Attachment Pad

Infrared / vapor phase

Reflow Soldering



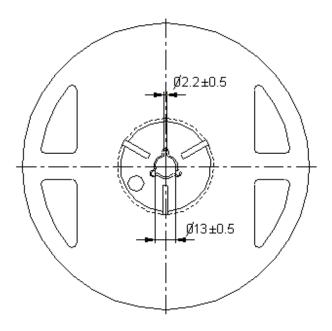
Package Dimensions of Tape



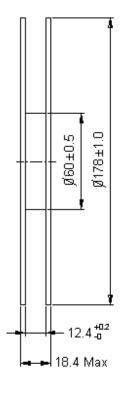
Note: All dimensions are in millimeters (inches).



■ Package Dimensions of Reel



Note: 01. The tolerance unless mentioned is±0.1mm 02. The measured unit is "mm"



Notes:

- 1. Empty component pockets sealed with top cover tape.
- 2. 7 inch reel-3000 pieces per reel.
- 3. Minimum packing quantity is 500 pieces for remainders.
- 4. The maximum number of consecutive missing lamps is two.
- 5. In accordance with EIA-481-1-B specifications.



10. Cautions

10.1 Application

The LEDs described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household applications). Consult Liteon's Sales in advance for information on applications in which exceptional reliability is required, particularly when the failure or malfunction of the LEDs may directly jeopardize life or health (such as in aviation, transportation, traffic control equipment, medical and life support systems and safety devices).

10.2 Storage

This product is qualified as Moisture sensitive Level 3 per JEDEC J-STD-020 Precaution when handing this moisture sensitive product is important to ensure the reliability of the product.

The package is sealed:

The LEDs should be stored at 30°C or less and 90%RH or less. And the LEDs are limited to use within one year, while the LEDs is packed in moisture-proof package with the desiccants inside.

The package is opened:

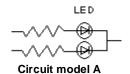
The LEDs should be stored at 30°C or less and 60%RH or less. Moreover, the LEDs are limited to solder process within 168hrs. If the Humidity Indicator shows the pink color in 10% even higher or exceed the storage limiting time since opened, that we recommended to baking LEDs at 60°C at least 24hrs. To seal the remainder LEDs return to package, it's recommended to be with workable desiccants in original package.

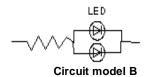
10.3 Cleaning

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED if necessary.

10.4 Drive Mode

An LED is a current-operated device. In order to ensure intensity uniformity on multiple LEDs connected in parallel in an application, it is recommended that a current limiting resistor be incorporated in the drive circuit, in series with each LED as shown in Circuit A below





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- (A) Recommended circuit.
- (B) The brightness of each LED might appear different due to the differences in the I-V characteristics of those LEDs.

10.5 ESD (Electrostatic Discharge)

Static Electricity or power surge will damage the LED. Suggestions to prevent ESD damage:

- Use of a conductive wrist band or anti-electrostatic glove when handling these LEDs.
- All devices, equipment, and machinery must be properly grounded.
- Work tables, storage racks, etc. should be properly grounded.
- Use ion blower to neutralize the static charge which might have built up on surface of the LED's plastic lens as a result of friction between LEDs during storage and handling.

ESD-damaged LEDs will exhibit abnormal characteristics such as high reverse leakage current, low forward voltage, or "no lightup" at low currents. To verify for ESD damage, check for "light up" and Vf of the suspect LEDs at low currents. The Vf of "good" LEDs should be >2.0V@0.1mA for InGaN product and >1.4V@0.1mA for AllnGaP product.

10.6 Suggested Checking List:

- Training and Certification
 - 1. Everyone working in a static-safe area is ESD-certified?
 - 2. Training records kept and re-certification dates monitored?
- Static-Safe Workstation & Work Areas
 - 1. Static-safe workstation or work-areas have ESD signs?
 - 2. All surfaces and objects at all static-safe workstation and within 1 ft measure less than 100V?
 - 3. All ionizer activated, positioned towards the units?
 - 4. Each work surface mats grounding is good?
- Personnel Grounding
 - 1. Every person (including visitors) handling ESD sensitive (ESDS) items wear wrist strap, heel strap or conductive shoes with conductive flooring?
 - 2. If conductive footwear used, conductive flooring also present where operator stand or walk?

Created Date: 03/01/2013 Revision: 16, 06/06/2014



- 3. Garments, hairs or anything closer than 1 ft to ESD items measure less than 100V*?
- 4. Every wrist strap or heel strap/conductive shoes checked daily and result recorded for all DLs?
- All wrist strap or heel strap checkers calibration up to date?Note: *50V for Blue LED.

Device Handling

- 1. Every ESDS items identified by EIA-471 labels on item or packaging?
- 2. All ESDS items completely inside properly closed static-shielding containers when not at static-safe workstation?
- 3. No static charge generators (e.g. plastics) inside shielding containers with ESDS items?
- 4. All flexible conductive and dissipative package materials inspected before reuse or recycle?

Others

- 1. Audit result reported to entity ESD control coordinator?
- 2. Corrective action from previous audits completed?
- 3. Are audit records complete and on file?

10.7 Others:

- Do not put any pressure on the light emitting surface either by finger or any hand tool and do not stack the products. Stress or pressure may cause damage to the wires of the LED array.
- This product is not designed for the use under any of the following conditions, please confirm the performance and reliability are well enough if you use it under any of the following conditions
- Do not use sulfur-containing materials in commercial products including the materials such as seals and adhesives that may contain sulfur.
- Do not put this product in a place with a lot of moisture (over 85% relative humidity), dew condensation, briny air, and corrosive gas (Cl, H₂S, NH₃, SO₂, NO_X, etc.), exposure to a corrosive environment may affect silver plating.
- The appearance and specifications of the product may be modified for improvement without prior notice.